WHAT IS CLAIMED IS:

1. A wiring board manufacturing method for manufacturing a wiring board on which a plurality of package device chips having electrodes are mounted, the wiring board having electrodes connected to the electrodes of the package device chips, the wiring board manufacturing method comprising:

a sheet laminate forming step of impregnating a glass cloth with a synthetic resin to form a plurality of sheets and stacking the sheets to form a sheet laminate having a first surface and a second surface;

a core member forming step of stacking a release plate on the first surface of the sheet laminate, stacking an electrode plate on the second surface of the sheet laminate, and pressing the release plate, the sheet laminate, and the electrode plate together in a stacked condition by moving a pressure plate into contact with the release plate or the electrode plate, thereby uniting the release plate, the sheet laminate, and the electrode plate to form a core member, and moving the pressure plate away from the release plate or the electrode plate after uniting the release plate, the sheet laminate, and the electrode plate to form the core member;

a front grinding step of grinding the release plate

of the core member as the front side of the core member in a condition where the electrode plate of the core member as the back side of the core member is held on a chuck table, thereby making a thickness of the core member uniform and removing all of the release plate to thereby form a flat surface on the front side of the core member; and

a first wiring layer forming step of forming a wiring layer on the flat surface formed in the front grinding step, the wiring layer being adapted to be connected to the package device chips.

2. The wiring board manufacturing method according to claim 1, further comprising:

a second wiring layer forming step of forming another wiring layer on the electrode plate of the core member after performing the first wiring layer forming step.

3. The wiring board manufacturing method according to claim 1, wherein the front grinding step is performed by using abrasive members, cutting tool, polishing belt, or cutting blade.

4. The wiring board manufacturing method according to claim 1, wherein the release plate is formed from a copper plate or a resin film.

5. The wiring board manufacturing method according to claim 1, further comprising:

a back grinding step of grinding the electrode plate of the core member as the back side of the core member after performing the front grinding step, thereby flattening the back side of the core member.

6. The wiring board manufacturing method according to claim 1, wherein the core member forming step of stacking a release plate on the first surface of the sheet laminate, stacking an electrode plate on the second surface of the sheet laminate, further includes pressing the release plate, the sheet laminate, and the electrode plate together in the stacked condition by moving a first pressure plate into contact with the release plate and a second pressure plate into contact with the electrode plate, thereby uniting the release plate, the sheet laminate, and the electrode plate to form a core member, and then moving the first pressure plate away from the release plate and the second pressure plate away from the electrode plate after uniting the release plate, the sheet laminate, and the electrode plate to form the core member.